

IN THE CLAIMS:

Please cancel Claims 12 to 16, 18, 19, 22, 36 to 40, 42, 43, 46, 57, 58, 60 to 62 and 64 to 72 without prejudice or disclaimer of the subject matter presented therein.

Please amend Claims 1, 9 to 11, 17, 20, 25, 33 to 35, 41, 44, 51, 55, 59 and 63 and add new Claims 73 to 80 as follows. A marked up copy of the amended claims, showing the changes made thereto, is attached. Note that all claims currently pending in this application, including those not currently being amended, have been reproduced below for the Examiner's convenience.

1. (Three Times Amended) A semiconductor device comprising a substrate, a filler, an exfoliative layer and a semiconductor element which is detachable from the substrate, wherein the exfoliative layer comprises an electron ray degradable resin.

2. (Unamended From Previous Version) The semiconductor device according to claim 1, which can be separated into (a) a laminate including the semiconductor element and (b) the substrate.

3. (Unamended From Previous Version) The semiconductor device according to claim 1, further comprising a protective layer, and which can be separated into (a) a laminate including the semiconductor element and (b) the protective layer.

4. (Amended) A process for producing a semiconductor device having a substrate, a filler, an exfoliative layer comprising an electron ray degradable resin, and a

semiconductor element; the process comprising the step of producing the semiconductor device in such a way that the semiconductor element is detachable from the substrate.

5. ~~10.~~ (Amended) The process according to claim ~~9~~⁴, which comprises the step of producing the semiconductor device so as to be detachable into a laminate having the semiconductor element, and the substrate.

6. ~~11.~~ (Amended) The process according to claim ~~9~~⁴, wherein the semiconductor device further has a protective layer, and which process comprises the step of producing the semiconductor device so as to be detachable into a laminate having the semiconductor element and the protective layer.

12. Cancelled.

13. Cancelled.

14. Cancelled.

15. Cancelled.

16. Cancelled.

C3 7. ~~17.~~ (Amended) A method of dismantling a semiconductor device having a substrate, a filler, an exfoliative layer comprising an electron ray degradable resin, and a semiconductor element; the method comprising detaching the semiconductor element from the substrate.

18. Cancelled.

19. Cancelled.

C4 8. ~~20.~~ (Amended) The method according to claim ~~17~~⁷, wherein the exfoliative layer is degraded to detach constituent members.

21. (Unamended From Previous Version) The method according to claim 20, which comprises the step of irradiating the exfoliative layer with electron rays.

22. Cancelled.

23. (Unamended From Previous Version) The method according to claim 20, wherein the semiconductor device further has a protective layer, and which method comprises the step of removing the filler remaining on the surface and/or back of the semiconductor element after separating the protective layer and/or substrate of the semiconductor device.

24. (Unamended From Previous Version) The method according to claim 23, wherein the filler is removed with an acid, an alkali or an organic solvent.

CS 12. ~~25.~~ (Three Times Amended) A solar cell module comprising a substrate, a filler, an exfoliative layer, a photovoltaic element which is detachable from the substrate, and a protective layer, wherein the exfoliative layer comprises an electron ray degradable resin.

26. (Unamended From Previous Version) The solar cell module according to claim 25, which can be separated into (a) a laminate including the photovoltaic element and (b) the substrate.

27. (Unamended From Previous Version) The solar cell module according to claim 25, which can be separated into (a) a laminate including the photovoltaic element and (b) the protective layer.

cb 15. ~~33.~~ (Amended) A process for producing a solar cell module having a substrate, a filler, an exfoliative layer comprising an electron ray degradable resin, a photovoltaic element and a protective layer; the process comprising the step of producing the solar cell module in such a way that the photovoltaic element is detachable from the substrate.

~~16.~~ ¹⁵34. (Amended) The process according to claim ~~33~~, which comprises the step of producing the solar cell module so as to be detachable into a laminate having the photovoltaic element, and the substrate.

C1 ~~17.~~ ¹⁵35. (Amended) The process according to claim ~~33~~, which comprises the step of producing the solar cell module so as to be detachable into a laminate having the photovoltaic element, and the protective layer.

36. Cancelled.

37. Cancelled.

38. Cancelled.

39. Cancelled.

40. Cancelled.

C8 ~~18.~~ ¹⁵41. (Amended) A method of dismantling a solar cell module having a substrate, a filler, an exfoliative layer comprising an electron ray degradable resin, a photovoltaic element and a protective layer; the method comprising detaching the photovoltaic element from the substrate.

42. Cancelled.

43. Cancelled.

C9 19. ~~44.~~ (Amended) The method according to claim ~~41~~¹⁸, wherein the exfoliative layer is degraded to detach constituent members.

45. (Unamended From Previous Version) The method according to claim 44, which comprises the step of irradiating the exfoliative layer with electron rays.

46. Cancelled.

47. (Unamended From Previous Version) The method according to claim 41, which comprises the step of removing the filler remaining on the surface and/or back of the photovoltaic element after separating the protective layer and/or substrate of the solar cell module.

48. (Unamended From Previous Version) The method according to claim 47, wherein the filler is removed with an acid, an alkali or an organic solvent.

C10 23. ~~51.~~ (Twice Amended) A semiconductor device comprising a substrate, a filler, an exfoliative layer and a semiconductor element, wherein at least one of the substrate, the filler and the semiconductor element can be detached from the other

C10
end
constituent members by irradiating the exfoliative layer with electron rays, and wherein the exfoliative layer comprises an electron ray degradable resin.

C11
~~55. (Twice Amended) A solar cell module comprising a substrate, a filler, an exfoliative layer, a photovoltaic element and a protective layer, wherein at least one of the substrate, the filler, the photovoltaic element and the protective layer can be detached from the other constituent members by irradiating the exfoliative layer with electron rays, and wherein the exfoliative layer comprises an electron ray degradable resin.~~

57. Cancelled.

58. Cancelled.

C12
24. ~~59.~~ (Amended) A method of dismantling a semiconductor device having a substrate, a filler, an exfoliative layer comprising an electron ray degradable resin, and a semiconductor element; the method comprising irradiating the exfoliative layer with electron rays to detach at least one of the substrate, the filler and the semiconductor element from the other constituent members.

60. Cancelled.

61. Cancelled.

62. Cancelled.

C.B. ~~25. 63.~~ (Amended) A method of dismantling a solar cell module having a substrate, a filler, an exfoliative layer comprising an electron ray degradable resin, a photovoltaic element and a protective layer; the method comprising irradiating the exfoliative layer with electron rays to detach at least one of the substrate, the filler, the photovoltaic element and the protective layer from the other constituent members.

64. Cancelled.

65. Cancelled.

66. Cancelled.

67. Cancelled.

68. Cancelled.

69. Cancelled.

70. Cancelled.

71. Cancelled.

72. Cancelled.

~~20.~~ ²³ ~~73.~~ (New) The semiconductor device according to claims 1 or ~~51~~, wherein the exfoliative layer comprises at least one selected from the group consisting of polyisobutylene, polymethyl styrene, polymethacrylate, polymethacrylonitrile and polyvinylidene chloride.

C14
~~21.~~ ¹² ~~74.~~ (New) The solar cell module according to claims ~~25~~ or ~~56~~, wherein the exfoliative layer comprises at least one selected from the group consisting of polyisobutylene, polymethyl styrene, polymethacrylate, polymethacrylonitrile and polyvinylidene chloride.

~~28.~~ ²³ ~~75.~~ (New) The semiconductor device according to Claims 1 or ~~51~~, wherein the exfoliative layer comprises at least one selected from the group consisting of polycarbonate, polyacetal and cellulose.

~~29.~~ ¹² ~~76.~~ (New) The solar cell module according to Claims ~~25~~ or ~~56~~, wherein the exfoliative layer comprises at least one selected from the group consisting of polycarbonate, polyacetal and cellulose.

~~30.~~ ^{4 15} ~~77.~~ (New) The process according to Claims ~~9~~ or ~~36~~, wherein the exfoliative layer comprises at least one selected from the group consisting of polyisobutylene, polymethyl styrene, polymethacrylate, polymethacrylonitrile and polyvinylidene chloride.